What is claimed is:

1. A printed wiring board comprising:

a substrate having two opposite surfaces, a plurality of soldering through holes formed in said substrate so as to open in said opposite surfaces, for inserting leads of an inserted component to be mounted onto the printed wiring board and soldering the inserted component onto said substrate, each of said through holes having an inner peripheral surface, and a plurality of lands each formed continuously across said opposite surfaces and the inner peripheral surface of a corresponding one of said through holes, each land having a surface; and

means for maintaining at least a part of the surface of each of said lands in a state not wetted by solder.

2. A printed wiring board as claimed in claim 1, further comprising at least one wiring pattern provided on at least one of said opposite surfaces and connected to said lands, and wherein said means maintains connection portions between said lands and said wiring pattern in a state not wetted by the solder.

3. A printed wiring board as claimed in claim 1, wherein said means comprises a material not wetted by the solder coated onto said lands.

4. A printed wiring board as claimed in claim 3,

wherein the material not wetted by the solder is a solder resist.

5. A printed wiring board as claimed in claim 3, wherein the material not wetted by the solder is a silk-printed pattern.

6. A printed wiring board as claimed in claim 3, wherein the material not wetted by the solder comprises a solder resist and a silk-printed pattern laminated onto one another.

7. A printed wiring board as claimed in claim 1, wherein said means comprises deactivation treatment means of oxidizing at least a part of the surface of each of said lands.

8. A printed wiring board as claimed in claim 1, wherein the leads of the inserted component have been treated with lead solder.

9. A printed wiring board as claimed in claim 1, wherein the inserted component is soldered onto said substrate by flow soldering using lead-free solder.

10. A printed wiring board as claimed in claim 9, wherein the lead-free solder contains Bi.

11. An electronic apparatus in which is installed a printed wiring board as claimed in claim 1.